Si1062X

RoHS

COMPLIANT

HALOGEN

FREE

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Marking code: J

PRODUCT SUMMARY						
V _{DS} (V)	20					
$R_{DS(on)}$ max. (Ω) at V_{GS} = 4.5 V	0.420					
$R_{DS(on)}$ max. (Ω) at V_{GS} = 2.5 V	0.492					
$R_{DS(on)}$ max. (Ω) at V_{GS} = 1.8 V	0.597					
$R_{DS(on)}$ max. (Ω) at V_{GS} = 1.5 V	0.762					
Q _g typ. (nC)	1					
I _D (A)	0.53					
Configuration	Single					

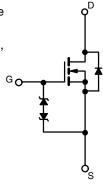
FEATURES

N-Channel 20 V (D-S) MOSFET

- TrenchFET® power MOSFET
- Gate-source ESD protected: 1000 V
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Load / power switching for portable devices
- Drivers: relays, solenoids, lamps, hammers, displays, memories
- Battery operated systems
- · Power supply converter circuits



N-Channel MOSFET

ORDERING INFORMATION	
Package	SC-89
Lead (Pb)-free and halogen-free	Si1062X-T1-GE3

ABSOLUTE MAXIMUM RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)						
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-source voltage		V _{DS}	20	V		
Gate-source voltage		V _{GS}	± 8	v		
Continuous drain current (T _J = 150 °C) ^a	T _A = 25 °C		0.53 ^{a, b}			
	T _A = 70 °C	ID	0.43 ^{a, b}	A		
Pulsed drain current (t = 300 µs)		I _{DM}	2	A		
Continuous source-drain diode current	T _A = 25 °C	IS	0.18 ^{a, b}			
Maximum power dissipation ^a	T _A = 25 °C	D	0.22 ^{a, b}	W		
Maximum power dissipation "	T _A = 70 °C	- P _D -	0.14 ^{a, b}	vv		
Operating junction and storage temperature r	T _J , T _{stg}	-55 to +150	°C			

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient ^b	t ≤ 5 s	R _{thJA}	440	530	°C/W	
Maximum junction-to-ambient ~	Steady state		540	650	C/W	

Notes

a. Surface mounted on 1" x 1" FR4 board

b. t = 5 s

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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 V, I_D = 250 \mu A$	20	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	L 050 ··· A	-	11	-	mV/°C	
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA	-	-1.8	-		
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	0.4	-	1	V	
Gate-source leakage	I _{GSS}	$V_{DS} = 0 V$, $V_{GS} = \pm 8 V$	-	-	± 30	μΑ	
Gate-source leakage		$V_{DS} = 0 V, V_{GS} = \pm 4.5 V$	-	-	± 1		
Zero gate voltage drain current	la an	$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	-	-	1		
Zero gate voltage drain current	IDSS	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 85 ^{\circ}\text{C}$	-	-	10		
On-state drain current ^a	I _{D(on)}	$V_{DS} = \geq 5 \text{ V}, \text{ V}_{GS} = 4.5 \text{ V}$	2	-	-	А	
		$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 0.5 \text{ A}$	-	0.350	0.420		
Drain-source on-state resistance ^a	Brach	$V_{GS} = 2.5 \text{ V}, \text{ I}_{D} = 0.2 \text{ A}$	-	0.410	0.492	Ω	
	R _{DS(on)}	$V_{GS} = 1.8 \text{ V}, I_D = 0.2 \text{ A}$	-	0.459	0.597		
		$V_{GS} = 1.5 \text{ V}, \text{ I}_{D} = 0.05 \text{ A}$	-	0.510	0.762		
Forward transconductance	9 _{fs}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 0.5 \text{ A}$	-	7.5	-	S	
Dynamic ^b							
Input capacitance	C _{iss}		-	43	-	pF	
Output capacitance	C _{oss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	14	-		
Reverse transfer capacitance	C _{rss}		-	8	-		
Total gate charge	0	V_{DS} = 10 V, V_{GS} = 8 V, I_{D} = 0.5 A	-	1.8	2.7		
Total gate charge	Qg		-	1	2	nC	
Gate-source charge	Q _{gs}	V_{DS} = 10 V, V_{GS} = 4.5 V, I_{D} = 0.5 A	-	0.16	-	110	
Gate-drain charge	Q _{gd}		-	0.13	-		
Gate resistance	R _g	f = 1 MHz	-	12.2	-	Ω	
Turn-on delay time	t _{d(on)}		-	2	4		
Rise time	t _r	$V_{DD} = 10 \text{ V}, \text{ R}_{L} = 20 \Omega,$	-	14	24	- ns	
Turn-off delay time	t _{d(off)}	$I_D \cong 0.4$ A, V_{GEN} = 4.5 V, R_g = 1 Ω	-	16	30		
Fall time	t _f		-	11	20		
Drain-Source Body Diode Characteris	stics						
Pulse diode forward current ^a	I _{SM}		-	-	2	А	
Body diode voltage	V _{SD}	I _S = 0.4 A	-	0.8	1.2	V	
Body diode reverse recovery time	t _{rr}		-	10	15	ns	
Body diode reverse recovery charge	Q _{rr}		-	2	4	nC	
Reverse recovery fall time	ta	I _F = 0.4 A, di/dt = 100 A/μs	-	5	-		
Reverse recovery rise time	t _b		-	5	-	ns	

Notes

a. Pulse test; pulse width $\leq 300~\mu\text{s},$ duty cycle $\leq 2~\%$

b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

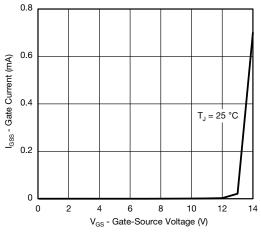
2



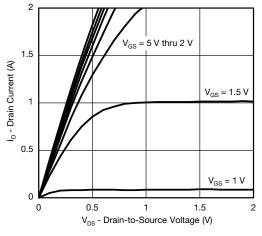
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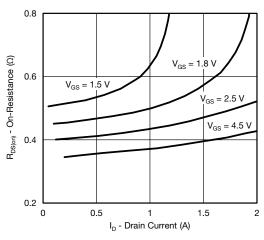
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



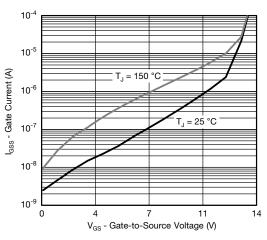
Gate Current vs. Gate-Source Voltage



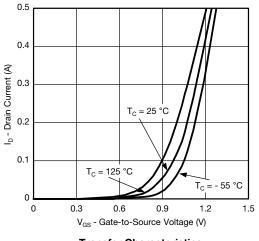
Output Characteristics



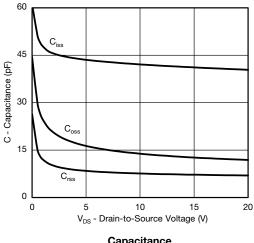
On-Resistance vs. Drain Current



Gate Current vs. Gate-Source Voltage



Transfer Characteristics



Capacitance

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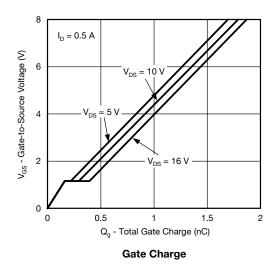
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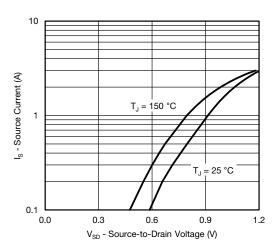
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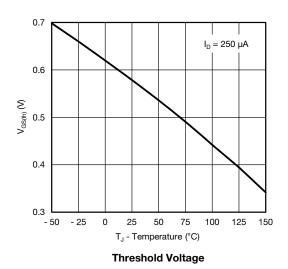
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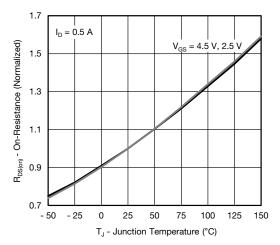
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



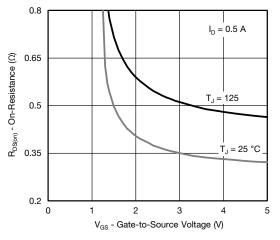


Source-Drain Diode Forward Voltage

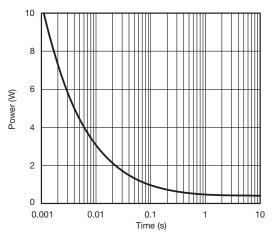




On-Resistance vs. Junction Temperature



On-Resistance vs. Gate-to-Source Voltage



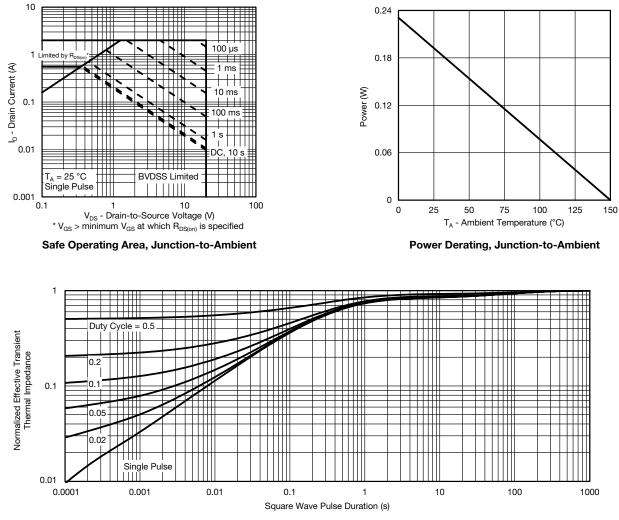
Single Pulse Power, Junction-to-Ambient

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient

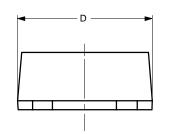
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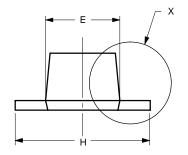
S12-2732-Rev. B, 12-Nov-12 Document Number: 62661 For technical questions, contact: pmostechsupport@vishay.com THIS DOCUMENT IS SUBJECT TO CHANGE WITHOUT NOTICE. THE PRODUCTS DESCRIBED HEREIN AND THIS DOCUMENT ARE SUBJECT TO SPECIFIC DISCLAIMERS, SET FORTH AT www.vishay.com/doc?91000

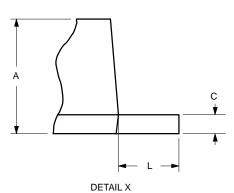
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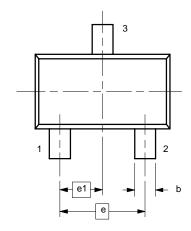


SC89-3









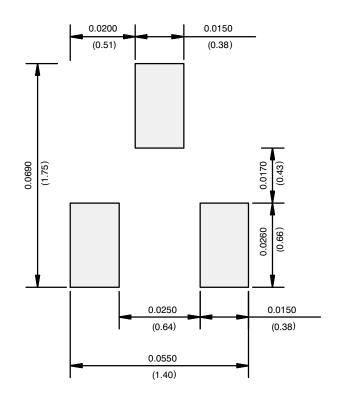
	MILLIN	IETERS	INCHES		
Dim	Min	Max	Min	Max	
Α	0.60	0.80	0.024	0.031	
b	0.23	0.33	0.009	0.013	
С	0.10	0.20	0.004	0.008	
D	1.50	1.70	0.059	0.067	
E	0.75	0.95	0.030	0.037	
е	1.00	BSC	0.040 BSC		
e ₁	0.50	BSC	0.020	BSC	
н	1.50	1.70	0.059	0.067	
L	0.30	0.50	0.012	0.020	
ECN: S-03946—Rev. B, 09-Jul-01 DWG: 5869					

Application Note 826

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RECOMMENDED MINIMUM PADS FOR SC-89: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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